



650V Super-junction Power MOSFET

Description

650V Super-junction Power MOSFET

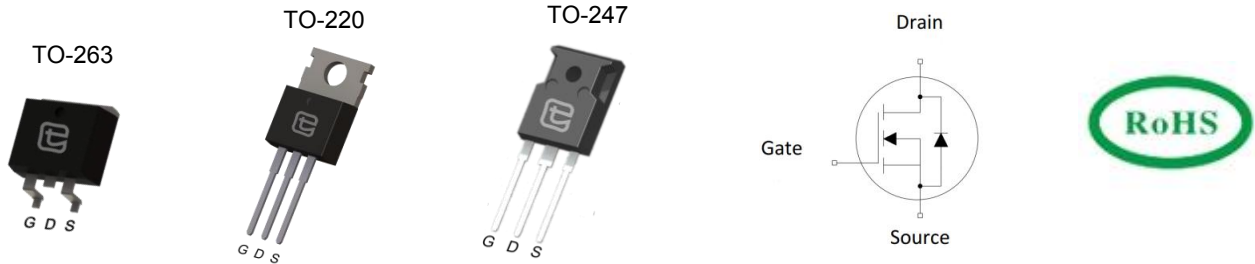
Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFETs, designed according to the SJ principle. The deep trench SJ MOSFET provide an extremely low switching, commutation and conduction losses device with highest robustness make especially resonant switching applications more reliable, more efficient, lighter and cooler, designed by Wuxi Unigroup Microelectronics Company

Features

- Ultra-fast body diode
- Very low FOM $R_{DS(on)} \times Q_g$
- Easy to use/drive
- 100% avalanche tested
- RoHS compliant

Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- LLC Half-bridge
- Charger



Device Marking and Package Information

Device	Package	Marking
TPB65R075DFD	TO-263	65R075DFD
TPP65R075DFD	TO-220	65R075DFD
TPW65R075DFD	TO-247	65R075DFD

Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	700	V
$R_{DS(on),max}$	0.075	Ω
$Q_{g,typ}$	81	nC
I_D	45	A
$I_{D,pulse}$	135	A
$E_{OSS} @ 400V$	10.29	μJ
t_{rr}	176	ns
Q_{rr}	1.4	μC
I_{rrm}	16	A



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted				
Parameter		Symbol	Values	Unit
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	45	A
	$T_C = 100^\circ\text{C}$		27	
Pulsed Drain Current	(note1)	$I_{D,pulse}$	135	A
Gate-Source Voltage		V_{GSS}	$\pm 30\text{V}$	V
Single Pulse Avalanche Energy	(note2)	E_{AS}	180	mJ
Repetitive Avalanche Energy	(note2)	E_{AR}	144	mJ
Avalanche Current		I_{AR}	6	A
MOSFET dv/dt Ruggedness, $V_{DS} = 0 \dots 650\text{V}$		dv/dt	50	V/ns
Power Dissipation For TO-263, TO-220, TO-247		P_D	312	W
Continuous Diode Forward Current		I_S	45	A
Diode Pulsed Current	(note1)	$I_{S,pulse}$	135	
Reverse Diode dv/dt	(note3)	dv/dt	50	V/ns
Operating Junction and Storage Temperature Range		T_J, T_{stg}	$-55 \sim +150$	$^\circ\text{C}$

Thermal Resistance For TO-263, TO-220, TO-247			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	0.4	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62	



Electrical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	650	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 650V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	10	μA
		$V_{DS} = 650V, V_{GS} = 0V, T_J = 150^\circ\text{C}$	--	--	5000	
Gate-Source Leakage Current	I_{GSS}	$V_{GS} = \pm 30V$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	--	4.5	V
Drain-Source On-State-Resistance	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 22A$	--	0.058	0.075	Ω
Gate Resistance	R_G	$f = 1.0\text{MHz}$ open drain	--	1	--	Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{GS} = 0V,$ $V_{DS} = 100V,$ $f = 1.0\text{MHz}$	--	4640	--	μF
Output Capacitance	C_{oss}		--	123	--	
Reverse Transfer Capacitance	C_{rss}		--	3.55	--	
Total Gate Charge	Q_g	$V_{DD} = 400V, I_D = 22A,$ $V_{GS} = 10V$	--	81	--	nC
Gate-Source Charge	Q_{gs}		--	25	--	
Gate-Drain Charge	Q_{gd}		--	24	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 400V, I_D = 22A,$ $R_G = 25\Omega$	--	107	--	ns
Turn-on Rise Time	t_r		--	80	--	
Turn-off Delay Time	$t_{d(off)}$		--	164	--	
Turn-off Fall Time	t_f		--	52	--	
Drain-Source Body Diode Characteristics						
Body Diode Forward Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{SD} = 22A, V_{GS} = 0V$	--	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R = 400V, I_S = 22A,$ $di_F/dt = 100A/\mu s$	--	176	--	ns
Reverse Recovery Charge	Q_{rr}		--	1.4	--	μC
Peak Reverse Recovery Current	I_{rrm}		--	16	--	A

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_D = 10A, V_{DD} = 50V, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. Identical low side and high side switch with identical R_G



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

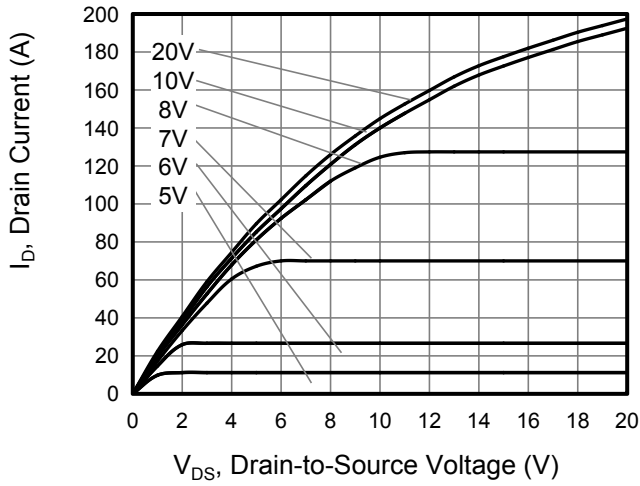


Figure 2. Transfer Characteristics

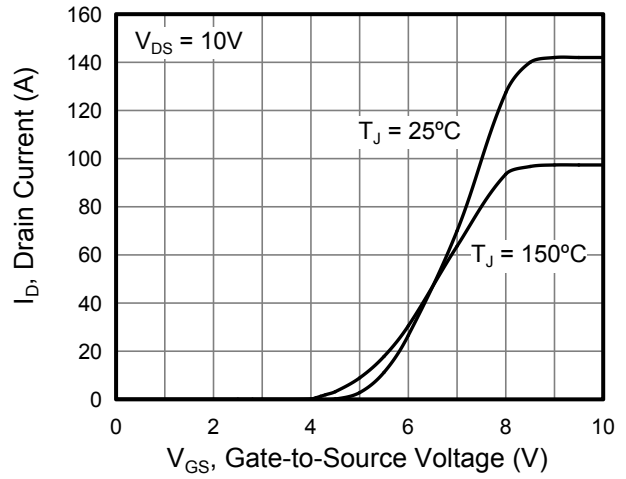


Figure 3 .On-Resistance vs. Drain Current

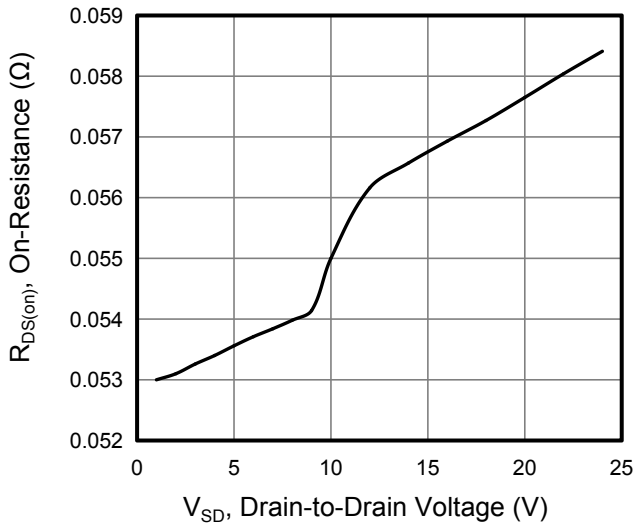


Figure 4. Capacitance

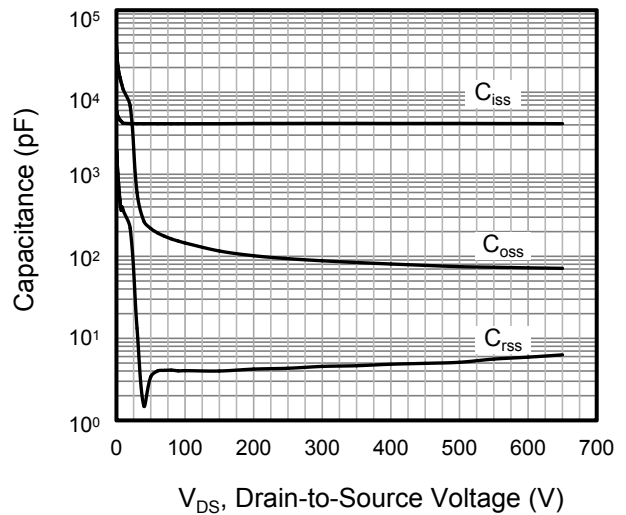


Figure 5. Gate Charge

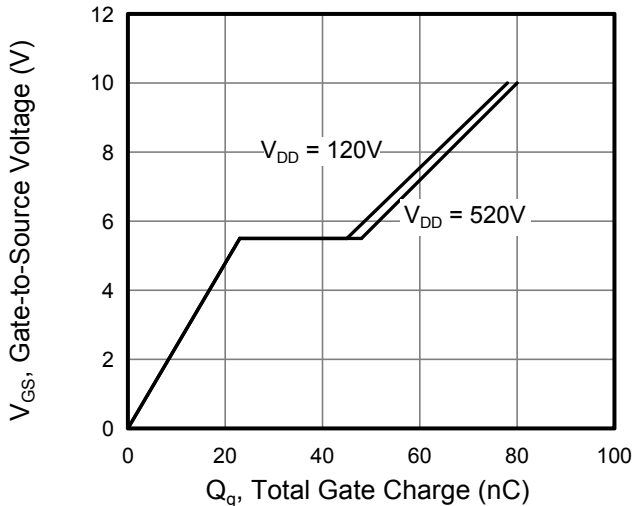


Figure 6. Body Diode Forward Voltage

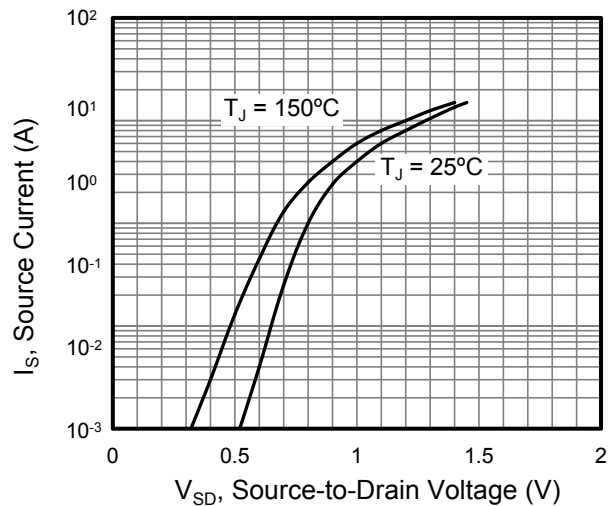




Figure 7. On-Resistance vs. Temperature

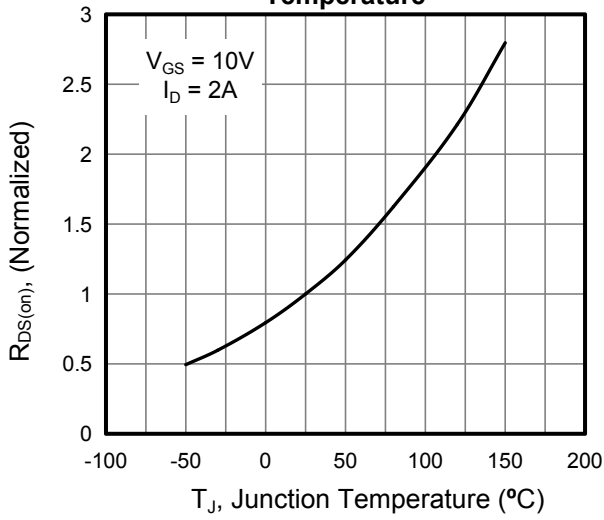


Figure 8. Breakdown voltage vs. Junction Temperature

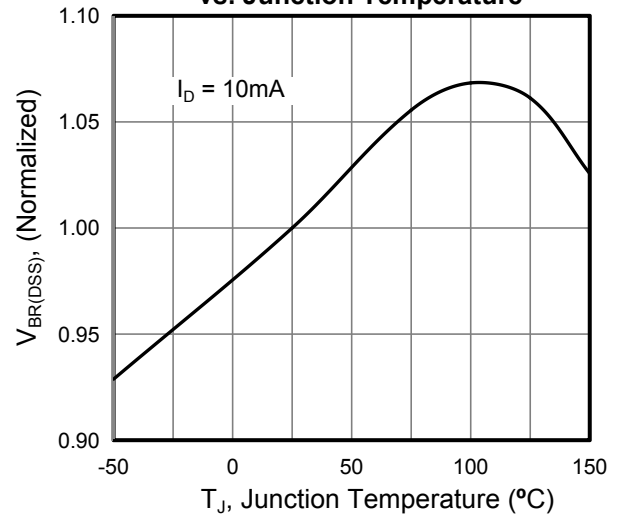


Figure 9. Transient Thermal Impedance For TO-263/TO-220/TO-247

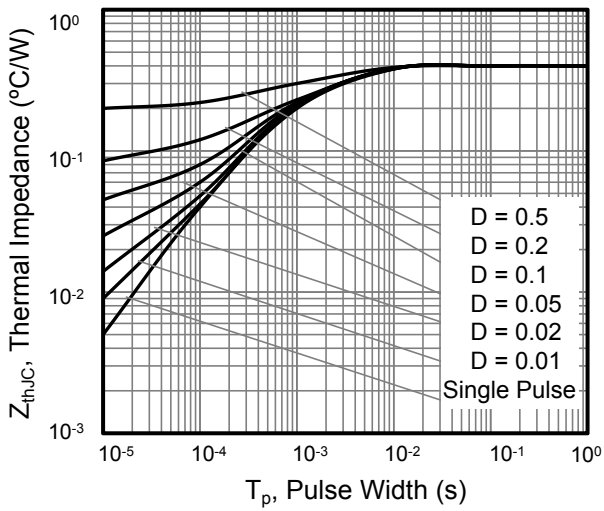


Figure 10. Safe Operation Area For TO-263/TO-220/TO-247

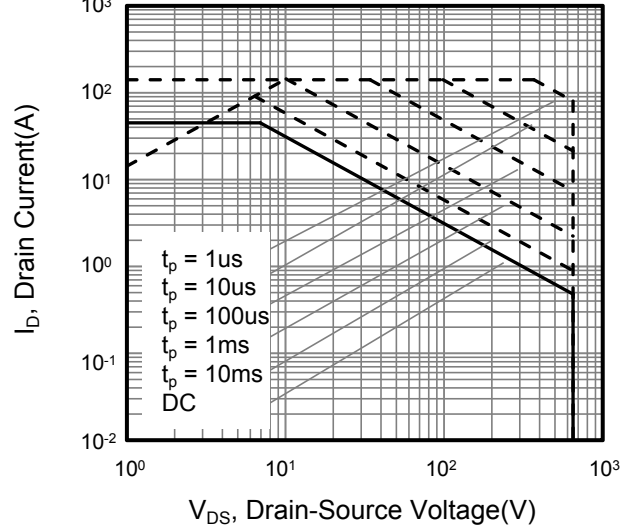


Figure 11. Typ. Coss Stored Energy

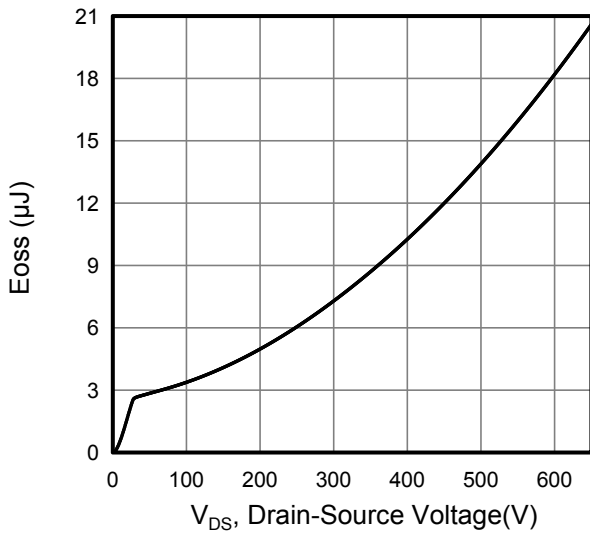




Figure A: Gate Charge Test Circuit and Waveform

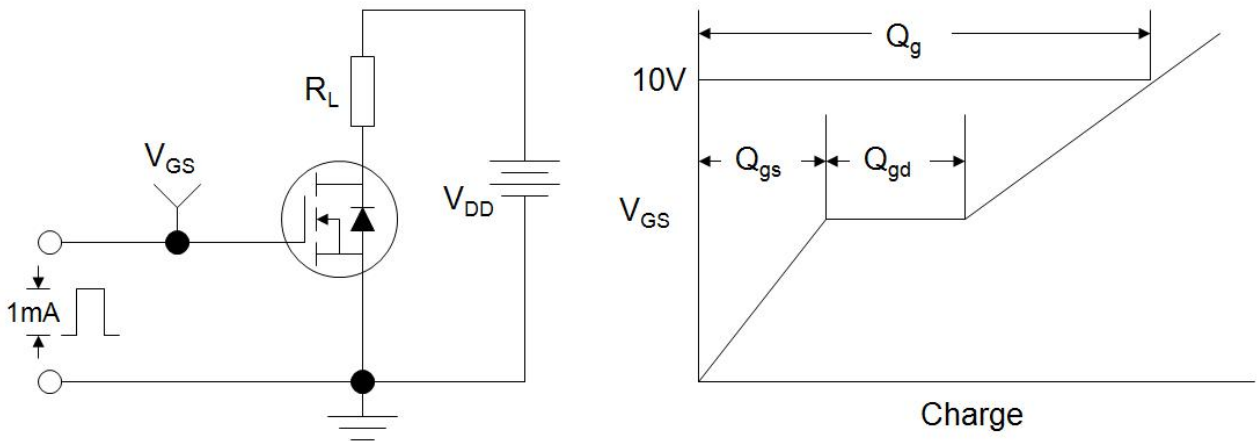


Figure B: Resistive Switching Test Circuit and Waveform

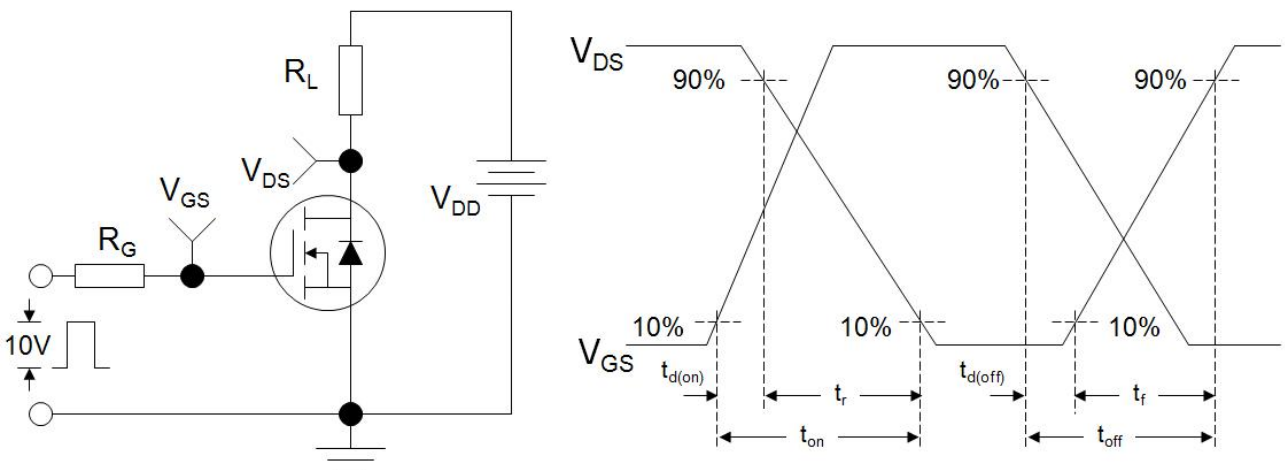
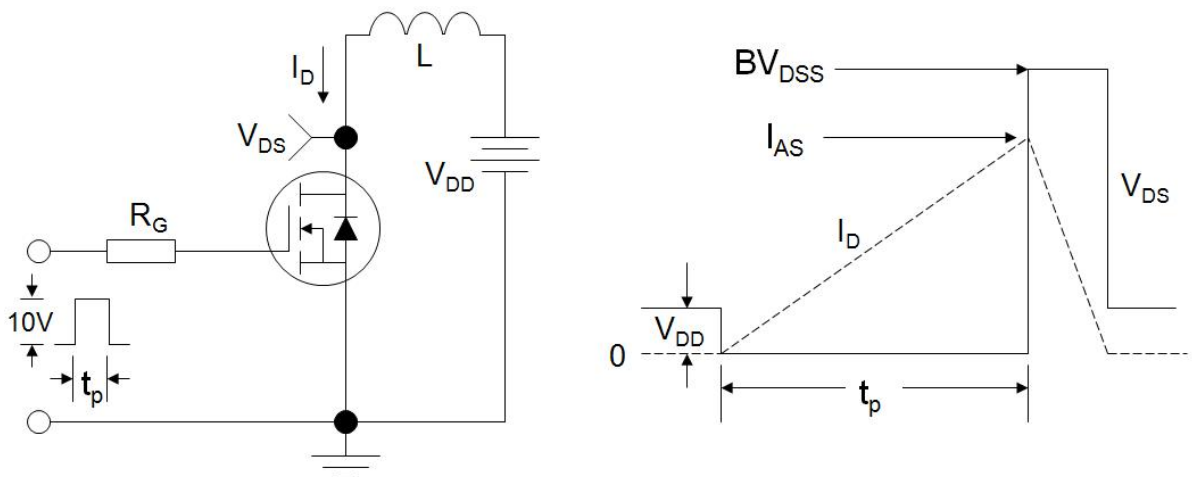
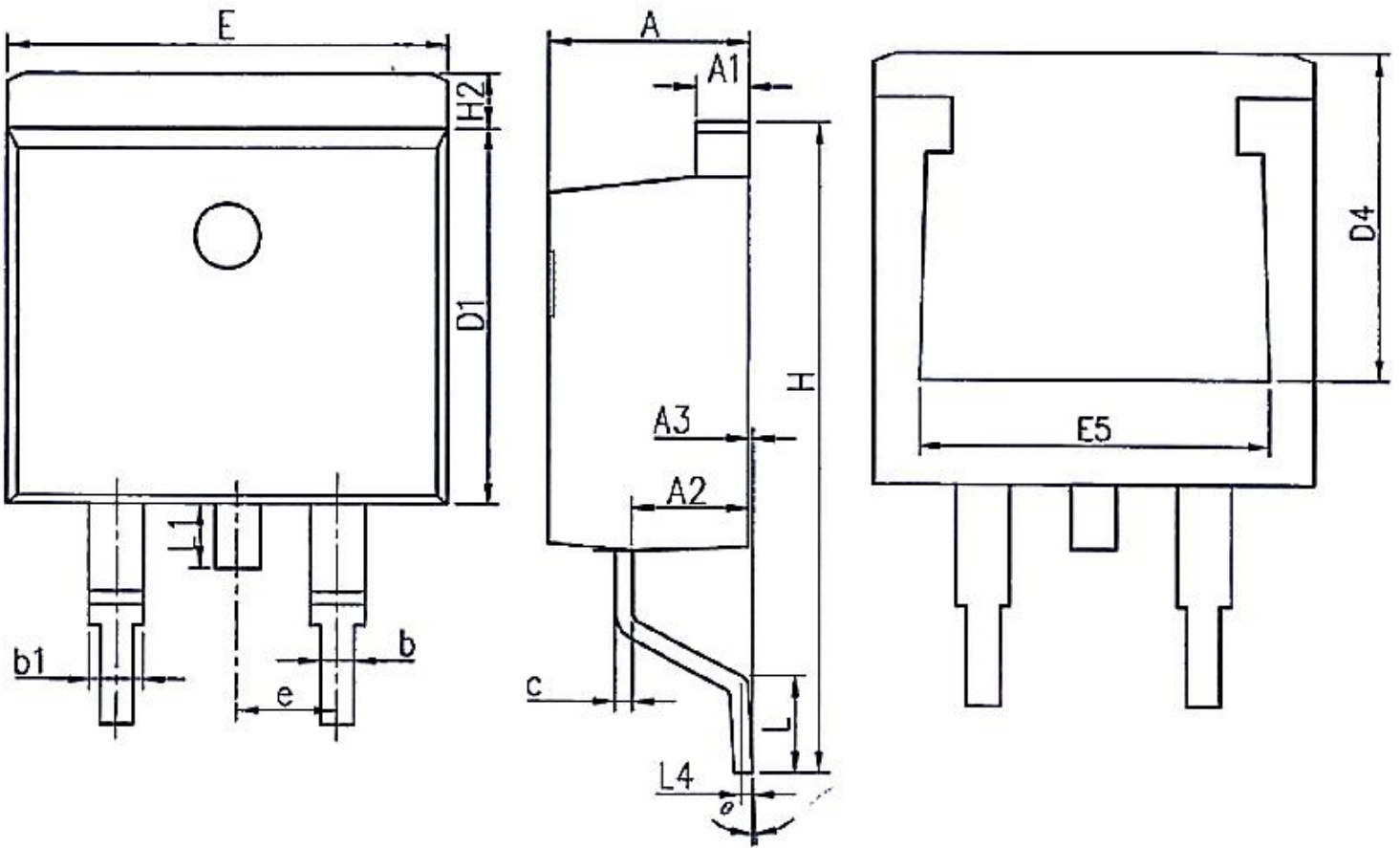


Figure C: Unclamped Inductive Switching Test Circuit and Waveform





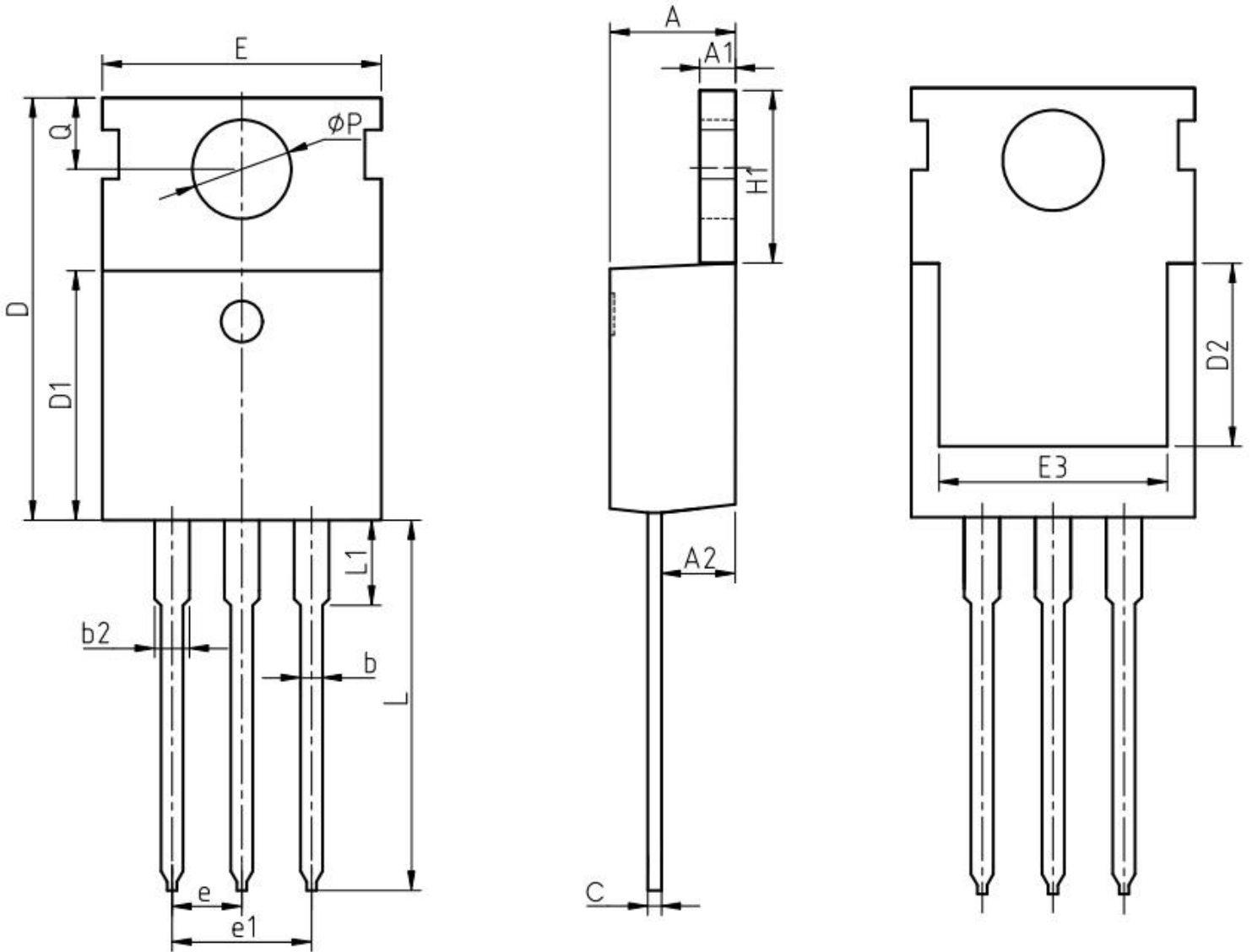
TO-263



Unit:mm				Unit:mm			
Symbol	Min.	Nom	Max.	Symbol	Min.	Nom	Max.
A	4.37	4.57	4.77	E	9.86	10.16	10.36
A1	1.22	1.27	1.42	E5	7.06	-	-
A2	2.49	2.69	2.89	e	2.54BSC		
A3	0.00	0.13	0.25	H	14.70	15.10	15.50
b	0.70	0.81	0.96	H2	1.07	1.27	1.47
b1	1.17	1.27	1.47	L	2.00	2.30	2.60
c	0.30	0.38	0.53	L1	1.40	1.55	1.70
D1	8.50	8.70	8.90	L4	0.25BSC		
D4	6.60	-	-	θ	0°	5°	9°



TO-220

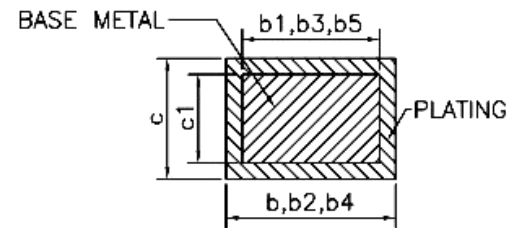
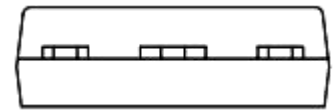
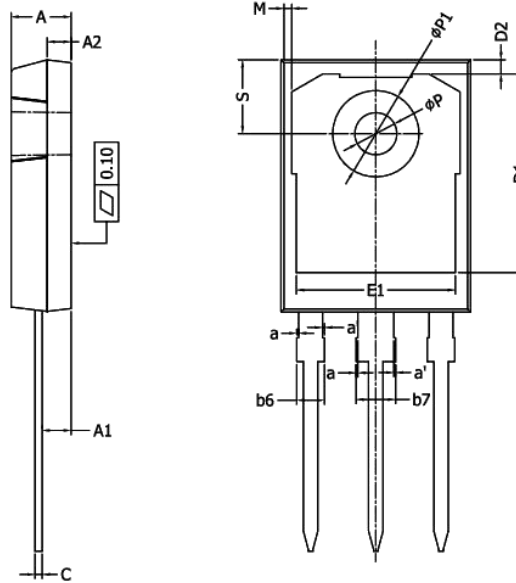
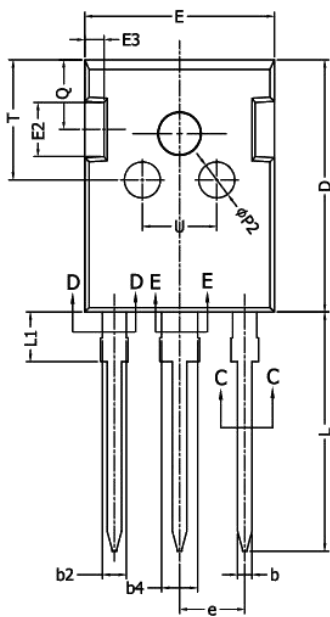


Unit:mm			
Symbol	Min.	Nom	Max.
A	4.37	4.57	4.77
A1	1.25	1.30	1.40
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b2	1.17	1.27	1.47
c	0.45	0.50	0.60
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50	-	-

Unit:mm			
Symbol	Min.	Nom	Max.
E	9.70	10.00	10.30
E3	7.00	-	-
e	2.54 BSC		
e1	5.08 BSC		
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1	-	3.10	3.40
ϕP	3.40	3.60	3.80
Q	2.60	2.80	3.00



TO-247



SYMBOL	MIN	NOM	MAX
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
a	0	---	0.15
a'	0	---	0.15
b	1.16	---	1.26
b1	1.15	1.2	1.22
b2	1.96	---	2.06
b3	1.95	2.00	2.02
b4	2.96	---	3.06
b5	2.96	3.00	3.02
b6	---	---	2.25
b7	---	---	3.25
c	0.59	---	0.66
c1	0.58	0.60	0.62
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.17	1.35
E	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	4.40	4.50	4.60
E3	2.40	2.50	2.60
e	5.436 BSC		
L	19.80	19.92	20.10
L1	---	---	4.30
M	0.35	---	0.95
P	3.40	3.50	3.60
P1	7.00	---	7.40
P2	2.40	2.50	2.60
Q	5.60	---	6.00
S	6.05	6.15	6.25
T	9.80	---	10.20
U	6.00	---	6.40



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